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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10084563	02/26/2002	438	682	2812	

\*\*APPLICANTS: Lopatin Sergey; Nickel Alexander; King Paul;

\*\*CONTINUING DATA VERIFIED:

NONE

\*\* FOREIGN APPLICATIONS VERIFIED:

NONE

PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no	P1410
Verified and Acknowledged Examiners's initials		
TITLE : Method of reducing electromigration by forming an electroplated copper-zinc interconnect and a semiconductor device thereby formed		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg. Print F
ISSUE FEE		Application Examiner	
Amount Due	Date Paid		
Primary Examiner			
PREPARED FOR ISSUE			
<input type="checkbox"/> TERMINAL DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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